

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

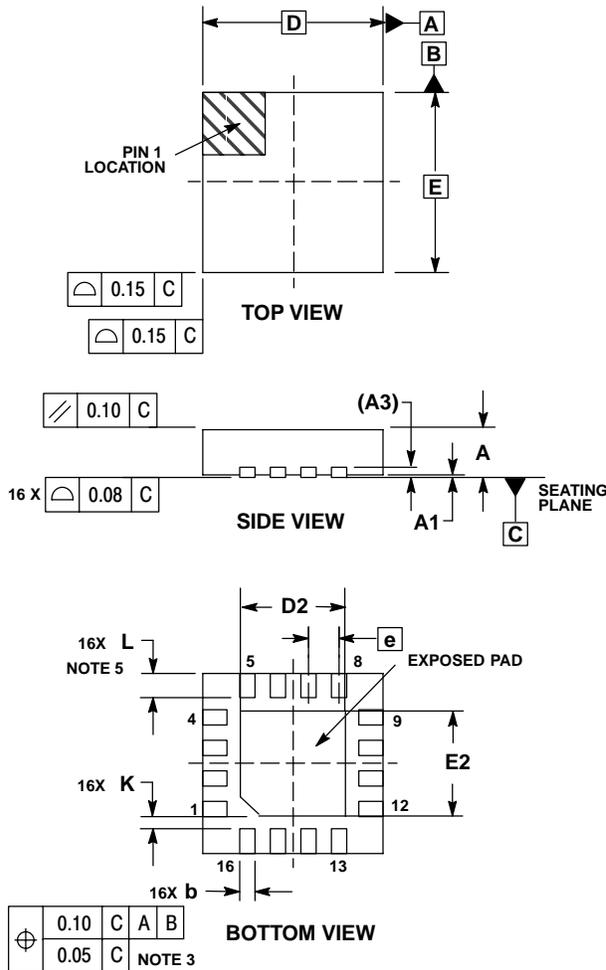


QFN16 3*3*0.75 MM, 0.5 P
CASE 488AK-01
ISSUE O

DATE 13 SEP 2004



SCALE 2:1

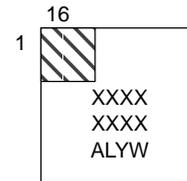


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. L_{max} CONDITION CAN NOT VIOLATE 0.2 MM SPACING BETWEEN LEAD TIP AND FLAG.

MILLIMETERS		
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.18	0.30
D	3.00	BSC
D2	1.65	1.85
E	3.00	BSC
E2	1.65	1.85
e	0.50	BSC
K	0.20	---
L	0.30	0.50

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN16, 3*3*0.75 MM, 0.5 PITCH	PAGE 1 OF 2

